



# SPECIFICATION FOR APPROVAL

CUSTOMER			
NOMINAL FREQUENCY	20.000000 MHz		
PRODUCT TYPE	TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL		
SPEC. NO. ( P/N )	FL2000038Q		
CUSTOMER P/N			
ISSUE DATE	August 30, 2018		
VERSION	В		

APPROVED	PREPARED	QA
Brenda	Kelly	Dong Jang

# **Diodes Incorporated**

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- \*Pb-free
- \*RoHS Compliant
- \*HF-Halogen Free
- \*REACH Compliant
- \*AEC-Q200 Compliant

E0-R-4-014 Rev. F

# TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL FL2000038Q

VER. B 30-Aug-18

# **VERSION HISTORY**

Version No.	Version Date	Description	Notes
А	Jul.29,2014	Initial Release	
В	Aug.30,2018	Updated logo	



E0-R-4-014 Rev. F

## FL2000038Q

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## **ELECTRICAL SPECIFICATIONS**

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	20.000000	MHz	
Mode of Oscillation	МО	AT Cut-Fundamental		
Calibration Load Capacitance	CL	16	pF	
Calibration Tolerance	FL	±10	ppm	at 25℃±3℃
Operating Temperature Range	TR	-20 to +85	C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±10	ppm	Reference to the Frequency at 25℃
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	50	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25℃		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	${\mathbb C}$	
Insulation Resistance		500	ΜΩ	Min
W. This product departs include harmful substance that etimulated by CONV.CC 00050 Level 4 and C. ATZ 000 Level 4 standard Dalif Compliant (Db. Esca)				

★ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



## FL2000038Q

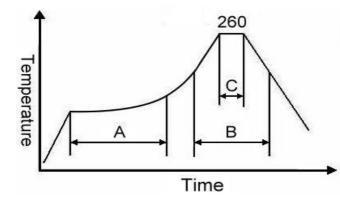
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#### **AEC-Q200 RELIABILITY TEST SPECIFICATIONS:**

- 1. Initial
- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet
- 2. Mechanical
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006
- 3. Environmental
- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

#### SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



N		

	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

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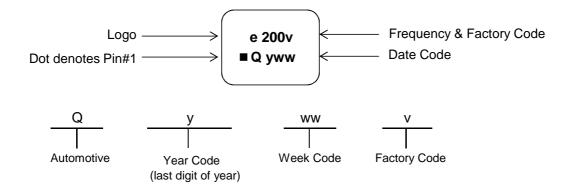
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## FL2000038Q

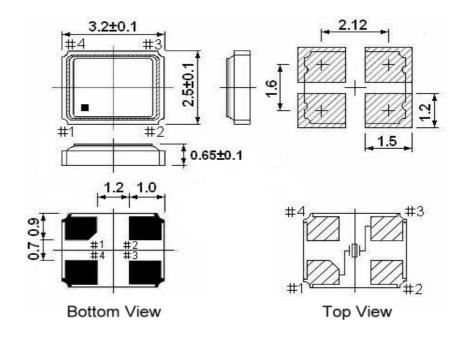
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#### **MARKING**



### **MECHANICAL DRAWINGS** (Scale: None. Dimensions are in mm.)

#### **Recommended Land Pattern**



\*\* Recommended - Pin 1 & 3 : CRYSTAL Pin 2 & 4 : GND

#### Notes:

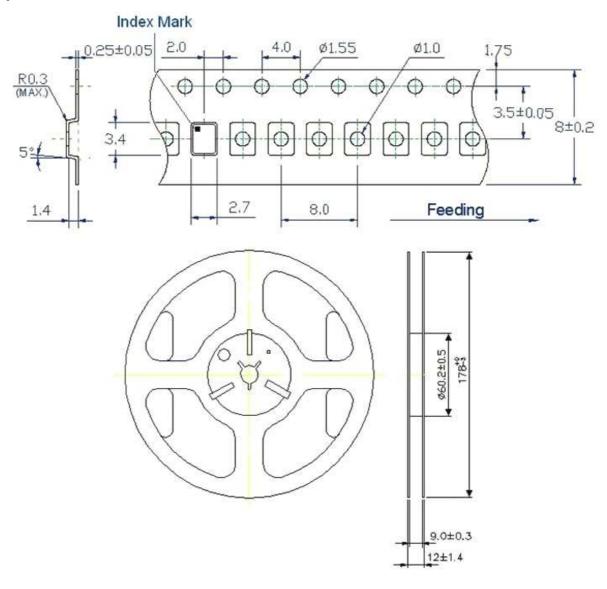
- Package drawings are for reference only, and the appearances of objects may vary.
  Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.

DODES

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## Tape & Reel



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

